

WHAT IS CLAIMED IS:

1. A mounting apparatus comprising:

a plurality of bonding stations, each of which has a bonding apparatus for bonding a semiconductor chip to a substrate wafer and a chip supply apparatus for supplying the semiconductor chip to the bonding apparatus; and

one wafer transfer apparatus for transferring the substrate wafer to supply the substrate wafer to each of the plurality of bonding stations and to collect the substrate wafer from each of the plurality of bonding stations,

wherein the bonding apparatus of each of the plurality of bonding stations is disposed adjacent to the wafer transfer apparatus, and

the chip supply apparatus of each of the plurality of bonding stations is disposed on an opposite side of the wafer transfer apparatus with the bonding apparatus interposed therebetween.

2. The mounting apparatus according to claim 1,

wherein the wafer transfer apparatus and the plurality of bonding stations cooperate with each other to form a chamber, and

the wafer transfer apparatus is capable of transferring the substrate wafer from one bonding station to another bonding station without exposing the substrate wafer to an outside of the chamber.

3. The mounting apparatus according to claim 1 or 2,

wherein the plurality of bonding stations comprise a first bonding station and a second bonding station disposed on an opposite side of the first bonding station with the wafer transfer apparatus interposed therebetween, and

the first bonding station, the wafer transfer apparatus, and the second bonding station are disposed side by side in a row.

4. The mounting apparatus according to any one of claims 1 to 3, further comprising:

one inspection apparatus for inspecting the substrate wafer that has been processed,

wherein the one inspection apparatus is shared by the plurality of bonding stations.

5. The mounting apparatus according to any one of claims 1 to 4,

wherein the wafer transfer apparatus comprises one transfer robot for transferring the substrate wafer and one pre-aligner for correcting a rotation angle of the substrate wafer, and

5           the one transfer robot and the one pre-aligner are shared by the plurality of bonding stations.

6. The mounting apparatus according to any one of claims 1 to 5,

wherein the wafer transfer apparatus has a transfer robot capable of holding two substrate wafers simultaneously, and

10           the transfer robot is capable of collecting a substrate wafer that has been processed at one bonding station and then supplying a new substrate wafer on the spot without moving.

7. The mounting apparatus according to any one of claims 1 to 6,

wherein the plurality of bonding stations comprise a first bonding station and a second bonding station, and

15           the wafer transfer apparatus supplies the substrate wafer that has been processed and collected from the first bonding station to the second bonding station.